



Final Product Change Notification

202202023F01 : For LPC18x0 and LPC43x0, TSMC Will be Added as a Second Source Wafer Fab

Note: This notice is NXP Company Proprietary.

Issue Date: Feb 24, 2022 **Effective date:** May 25, 2022

Management summary

For LPC18x0 and LPC43x0 (Flashless), TSMC will be added as a second source wafer fab.

Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata |
| <input checked="" type="checkbox"/> Wafer Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

PCN Overview

Description

For LPC18x0 and LPC43x0 products, The current wafer fab is UMC. TSMC has been qualified and will be added as a second source wafer fab.

- No change in data sheet
- No change in ordering part number / 12NC
- Final test location remains unchanged at NXP Assembly and Test Kaohsiung (ATKH)

Reason

To ensure wafer supply with increased capacity.

Identification of Affected Products

Top Side Marking

The wafer fab can be identified on the top side marking. The first character of the 3rd line in the top side marking is the fab code. E = TSMC, 9 = UMC

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment May 19, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

After the PCN effective date, customers may receive product from either wafer fab.

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Mar 26, 2022.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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